

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5108508

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JOANNA CHAW YANE YIN	07/25/2012
CHI-HSI WU	07/25/2012
KUO-CHIANG TING	07/27/2012
KUANG-HSIN CHEN	07/25/2012
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16111408
CORRESPONDENCE DATA	
Fax Number:	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Correspondent Name:	HAYNES AND BOONE, LLP IP SECTION
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Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	20111215 / 24061.2813US05
NAME OF SUBMITTER:	JANIE MARTINEZ-HOLM
SIGNATURE:	/Janie Martinez-Holm/
DATE SIGNED:	08/24/2018
Total Attachments: 3	

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Docket No.: 2011-1215 / 24061.2050
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- | | | |
|-----|-------------------------|---|
| (1) | Joanna Chaw Yane Yin of | No. 168, Science Park 2nd Road
Hsinchu 300, R.O.C. |
| (2) | Chi-Hsi Wu of | No. 26, Lane 862, Nan-Da Road
Hsinchu City 300, Taiwan, R.O.C. |
| (3) | Kuo-Chiang Ting of | 12F-3, No 90, Daxue Road
Hsinchu City 300, Taiwan, R.O.C. |
| (4) | Kuang Hsin Chen of | 440, Chun-Fu Road
Jung-Li City, Taiwan, R.O.C. |

have invented certain improvements in

METHOD OF MAKING A FINFET DEVICE

for which we have filed and executed an application for Letters Patent of the United States of America on June 6, 2012, as U.S. Serial No. 13/490,108; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue

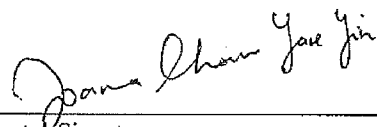
Docket No.: 2011-1215 / 24061.2050
Customer No.: 42717

applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Joanna Chaw Yane Yin

Residence Address: No. 168, Science Park 2nd Road
Hsinchu 300, Taiwan, R.O.C.

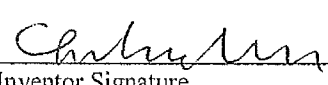
Dated: 25 JUL 2012


Inventor Signature

Inventor Name: Chi-Hsi Wu

Residence Address: No. 26, Lane 862, Nan-Da Road
Hsinchu City 300, Taiwan, R.O.C.

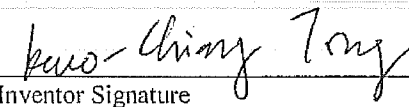
Dated: 7/25 2012


Inventor Signature

Inventor Name: Kuo-Chiang Ting

Residence Address: 12F-3, No 90, Daxue Road
Hsinchu City 300, Taiwan, R.O.C.

Dated: 7/25 2012


Inventor Signature

Docket No.: 2011-1215 / 24061.2050
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Inventor Name: Kuang-Hsin Chen
Residence Address: 440, Chun-Fu Road
Jung-Li City, Taiwan, R.O.C.

Dated: 2012/07/25

陳光鑫 Chen, Kuang-hsin
Inventor Signature
